

SURFBOARDS[®]

THE BREADBOARDING MEDIUM FOR **SURFACE MOUNT**™



33000 SERIES APPLICATION SPECIFIC ADAPTERS

IDS33305
REV A-10-2011

MODEL **33305**

ACCEPTS **SOT-953**

PARTIAL LISTING

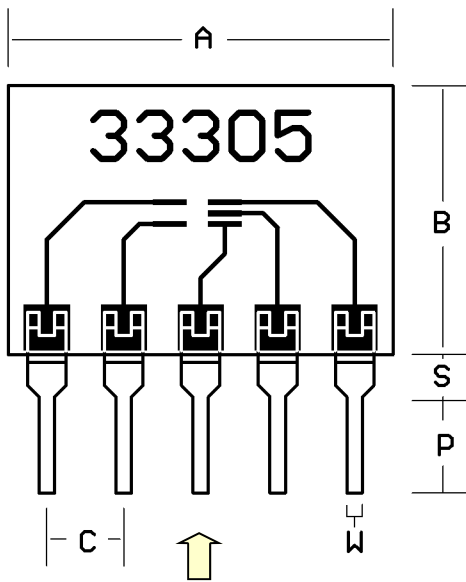
5 LEAD .35 mm PITCH DEVICES
DEVICE LEAD WIDTH 1.0 To Max 2.5 MM

ALWAYS CONSULT DEVICE DATA SHEET TO INSURE PROPER FIT

Pins on .1 in. Centers designed for use with Solderless breadboards, Conventional Breadboards, and Sockets with standard .1 in. centers.

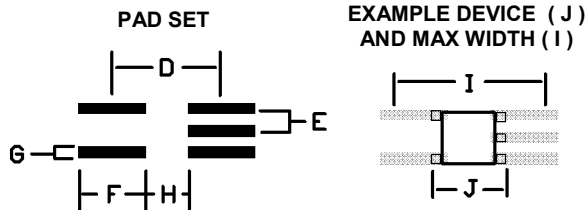
Use For Prototyping, Device Test or Evaluation and SMD to Through Hole Conversion.

Oversize Pads Permit hand soldering and accept a wide range of device widths and tolerances.



SINGLE-IN-LINE (SIP) PINS
ON .100 in. CENTERS

DRAWINGS
NOT TO
SCALE



MOUNTING PADS ARE OVERSIZED IN LENGTH TO ACCEPT A WIDER RANGE OF DEVICE WIDTHS AND TOLERANCES AND TO PERMIT HAND SOLDERING.

[SEE WEBSITE FOR SOLDERING SUGGESTIONS](#)

| FIG. | MM | IN. | NOTE: |
|------|------|------|---------------------------------------|
| A | 12.7 | .500 | BOARD WIDTH +/- .5mm .020in. |
| B | 8.89 | .350 | BOARD HEIGHT +/- .5mm .020in. |
| C | 2.54 | .100 | SIP PIN SPACE +/- .20mm .008in. |
| D | 1.8 | .071 | PAD CENTERLINE |
| E | .35 | .014 | DEVICE LEAD PITCH |
| F | 1.1 | .043 | PAD LENGTH |
| G | .2 | .008 | PAD WIDTH |
| H | .7 | .028 | GAP |
| I | 2.5 | .098 | MAX LEAD WIDTH |
| J | 1.0 | .039 | TYPICAL LEAD WIDTH |
| P | 3.3 | .130 | LENGTH FROM SHOULDER +/- .5mm .020in. |
| S | 1.57 | .062 | PIN SHOULDER HEIGHT |
| W | .5 | .020 | PIN WIDTH |

TOLERANCES: If not noted are +/- 20%. Nominal values are given. Controlling unit is Millimeters. Slight Variations due to manufacturing process can occur.

BOARD SPECIFICATIONS

BOARD MATERIAL: .8mm, +/- .13mm .031in +/- .005 in. Thick G-10 FR-4 Glass Epoxy or equivalent.

CIRCUITS: 1 oz. Copper with RoHS compliant Lead Free solder coating. Patten Position on board +/- .5mm .020in.



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